EXPOSURE APPARATUS, MOVABLE BODY DRIVE SYSTEM, PATTERN FORMATION APPARATUS, EXPOSURE METHOD, AND DEVICE MANUFACTURING METHOD

ABSTRACT

While a wafer stage (WST) moves linearly in a Y-axis direction, surface position information of a wafer (W) surface at a plurality of detection points set at a predetermined interval in an X-axis direction is detected by a multipoint AF system (90), and by a plurality of alignment systems (AL1, $AL2_1$ to $AL2_4$) arranged in a line along the X-axis direction, marks at different positions on the wafer are each detected, and a part of a chipped shot of the wafer is exposed by a periphery edge exposure system (51). This allows throughput to be improved when compared with the case when detection operation of the marks, detection operation of the surface position information (focus information), and periphery edge exposure operation are performed independently.

Fig. 5